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**INFORMATION
DISCLOSURE
STATEMENT**

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Serial No.: Unknown

Applicant(s): Sanjay L. PATIL et al.

Filing Date: Herewith

Group:

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Sub-Class	Filing Date if Appropriate
g	3,853,467	12/10/1974	Glaever			
	3,926,564	12/16/1975	Glaever			
	3,979,509	09/07/1976	Glaever			
	4,266,108	05/05/1981	Anderson et al.			
	4,387,156	06/07/1983	Crawford et al.			
	4,390,343	06/28/1983	Walter			
	4,649,280	03/10/1987	Holland et al.			
	4,985,300	01/15/1991	Huang			
	5,143,854	09/01/1992	Pirung et al.			
	5,192,502	03/09/1993	Attridge et al.			
	5,278,377	01/11/1994	Tsai			
✓	5,317,045	05/31/1994	Clark, Jr. et al.			

FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Sub-Class	Translation	
					Yes	No
JP 63-301988 A	12/08/1988	Japan				
GB 2 065 298 A	06/24/1981	United Kingdom				
WO94/16803 A	08/04/1994	PCT				
WO 95/11912 A	05/04/1995	PCT				
WO 99/32663 A	07/01/1995	PCT				
WO 99/53319 A2	10/21/1999	PCT				
WO 99/53319 A3	10/21/1999	PCT				

OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

g	U.S. Serial No. 09/287,379, entitled "HIGH DENSITY, MINIATURIZED ARRAYS AND METHODS OF MANUFACTURING SAME," filed April 7, 1999.
	U.S. Serial No. 09/459,418, entitled "HEAT-RELAXABLE SUBSTRATES AND ARRAYS," filed December 9, 1999.
✓	U.S. Serial No. 09/519,450, entitled "MATERIALS WITH SILICON-CONTAINING LAYERS FOR USE IN MINIATURIZED ARRAYS AND METHODS OF MANUFACTURING," filed March 5, 2000.

EXAMINER

J. Goldberg

Date Considered

3/19/03

* Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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